

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
WOOKWANG LEE	01/15/2018
BYUNGJUN KIM	01/15/2018
DONGRAK SHIN	01/15/2018
JAEJIN LEE	01/15/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAMSUNG ELECTRONICS CO., LTD.
<b>Street Address:</b>	129, SAMSUNG-RO, YEONGTONG-GU, SUWON-SI,
<b>City:</b>	GYEONGGI-DO, 16677
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15926932
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	972-628-3600
<b>Email:</b>	patents@munckwilson.com
<b>Correspondent Name:</b>	DOCKET CLERK
<b>Address Line 1:</b>	P.O. DRAWER 800889
<b>Address Line 4:</b>	DALLAS, TEXAS 75380
<b>ATTORNEY DOCKET NUMBER:</b>	YPF201711-0034-US
<b>NAME OF SUBMITTER:</b>	JACOB L. LACOMBE
<b>SIGNATURE:</b>	/Jacob L. LaCombe/
<b>DATE SIGNED:</b>	03/20/2018
<b>Total Attachments: 2</b>	
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DOCKET NO.: YPF201711-0034-US (SAMS07-11034)  
Client Ref.: GM-201702-010-1-US0

PATENT

ASSIGNMENT

WHEREAS, We, Wookwang LEE, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, Byungjun KIM, resident of Seongdong-gu, Seoul, Republic of Korea, citizen of Republic of Korea, Dongrak SHIN, resident of Gwangju-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea and Jaejin LEE, resident of Seongbuk-gu, Seoul, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a "ELECTRONIC DEVICE AND METHOD FOR CONTROLLING EXTERNAL ELECTROINC DEVICE CONNECTED TO USB TYPE-C CONNECTOR" disclosed in an application for United States Letters Patent (Application No. \_\_\_\_/\_\_\_\_\_, filed on \_\_\_\_\_, said application having been executed concurrently herewith;

WHEREAS, SAMSUNG ELECTRONICS CO., LTD, a corporation organized under the laws of the Republic of Korea, having a place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 16677, Republic of Korea (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEE of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

We hereby further agree that we will communicate to said ASSIGNEE, or to its successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, and make all

lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

Date: Jan 15, 2018

Wookwang Lee  
Wookwang LEE

Date: Jan 15, 2018

ByungJun Kim  
Byungjun KIM

Date: Jan 15, 2018

Dongrak Shin  
Dongrak SHIN

Date: Jan 15, 2018

Jaejin Lee  
Jaejin LEE